

DATASHEET

Technical Data Sheet Infrared MIDLED LED EAIST3122A1

Features

- Low forward voltage.
- View angle 30°(Typ.)
- Pb free
- The product itself will remain within RoHS compliant version.
- Compatible with infrared and vapor phase reflow solder process.

Description

• EAIST3122A1 is an infrared emitting diode with miniature MIDLED package. The device is spectrally matched with silicon photodiode and phototransistor

Applications

• Infrared applied system

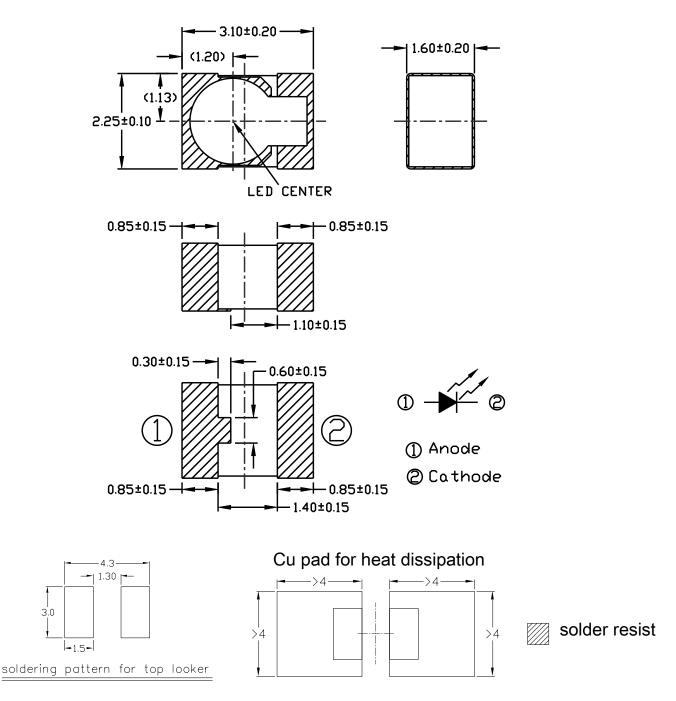
Device Selection Guide

Device No.	Chip Material	Lens Color
EAIST3122A1	GaAlAs	Water clear





Package Dimensions



Notes: 1.All dimensions are in millimeters

2. Tolerances unless dimensions ±0.1mm



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Continuous Forward Current	I_{F}	80	mA
Peak Forward Current *1	I_{FP}	800	mA
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	-40 ~ +100	$^{\circ}\mathbb{C}$
Storage Temperature	T_{stg}	-40 ~ +100	$^{\circ}\mathbb{C}$
Soldering Temperature *2	T_{sol}	260	$^{\circ}\mathbb{C}$
Power Dissipation at(or below) 25°C Free Air Temperature	P _d	170	mW

Notes: *1: I_{FP} Conditions--Pulse Width $\leq 100 \mu$ s and Duty $\leq 1\%$.

*2: Soldering time ≤ 5 seconds.

Electro-Optical Characteristics (Ta=25 $^{\circ}$ C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
D. P. J. J. J.	40 60 125	****	I _F =70mA			
Radiant Intensity	Ie	45	70		mW/sr	. $I_F\!\!=\!\!100mA$ Pulse Width $\!\leq\!100\mu$ s ,Duty $\!\leq\!1\%$
Peak Wavelength	λр		940		nm	$I_F=100mA$
Spectral Bandwidth	Δλ		40		nm	I _F =100mA
Forward Voltage	V_{F}		1.75	2.2	V	I _F =100mA
Reverse Current	I_R			10	μА	V _R =5V
View Angle	2θ1/2		30		deg	I _F =20mA

Rank

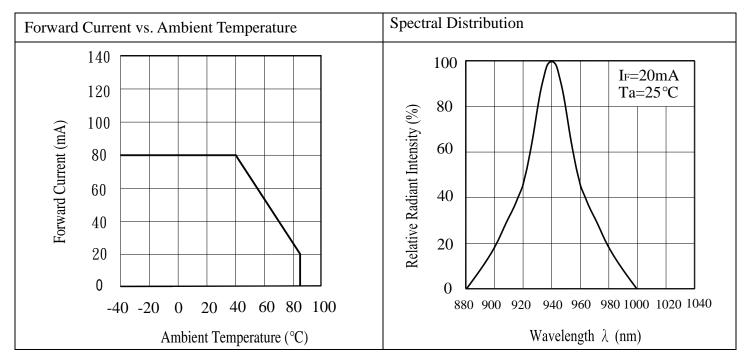
Condition : $I_F=70mA$

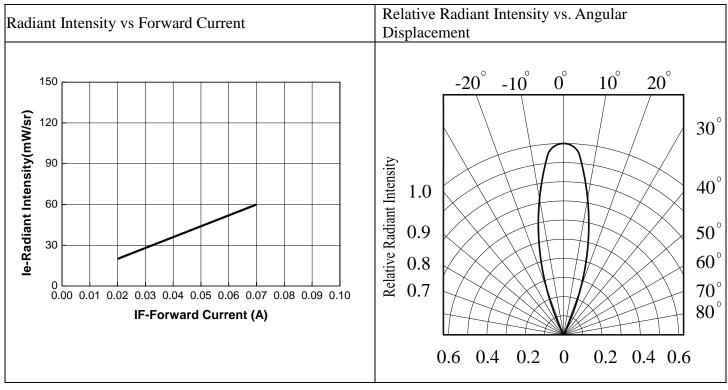
Unit: mW/sr

Bin Number	C	D
Min	40	63
Max	80	125

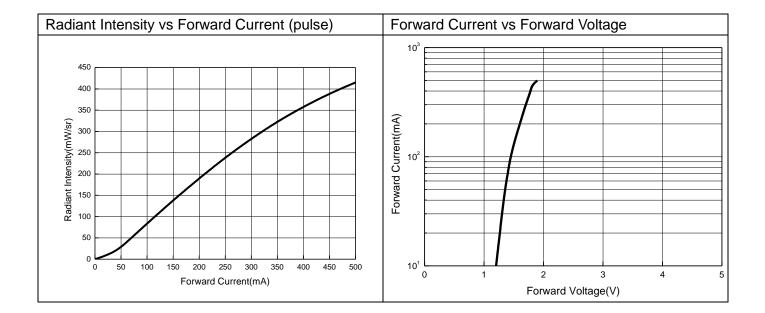


Typical Electrical/Optical/Characteristics Curves for IR











Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

- 2.1 Do not open moisture proof bag before devices are ready to use.
- 2.2 Shelf life in sealed bag from the bag seal date: 18 onths at 10°C~30°C and < 90% RH.
- 2.3 After opening the package, the devices must be stored at 10°C~30°C and 60%RH, and used within 72 hours(floor life).
- 2.4 If the moisture absorbent material(desiccant material) has faded or unopened bag has exceeded the shelf life or devices(out of bag) have exceeded the floor life, baking treatment is required.
- 2.5 If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure or recommend the following conditions:

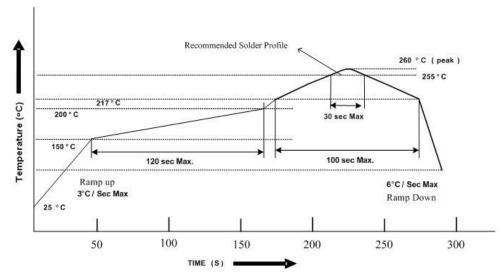
192 hours at $40^{\circ}\text{C} + 5/-0^{\circ}\text{C}$ and < 5 % RH (reeled/tubed/loose units) or

96 hours at $60^{\circ}\text{C} \pm 5^{\circ}\text{C}$ and $< 5^{\circ}\text{K}$ RH (reeled/tubed/loose units) or

24 hours at 125 °C \pm 5 °C, not suitable for reel or tubes.

3. Soldering Condition

3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

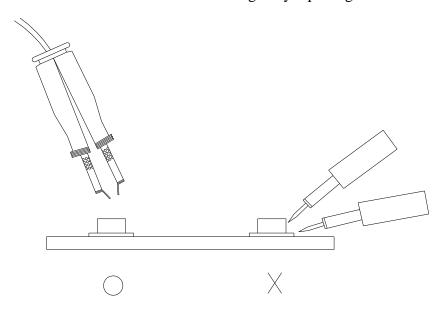


4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

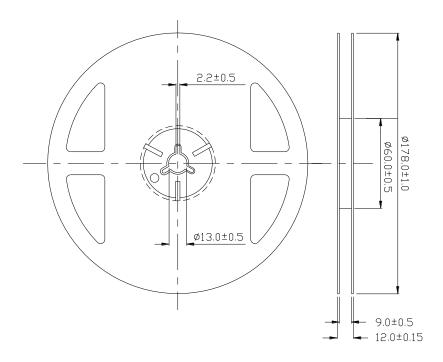
5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



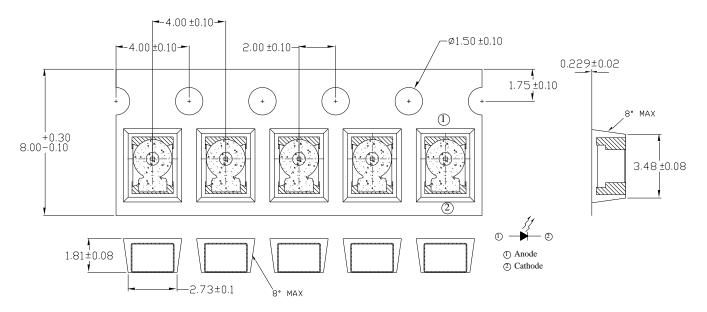


Package Dimensions



Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm

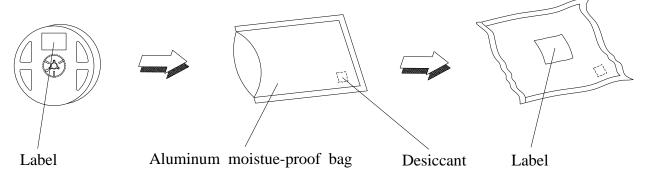
2. Carrier Tape Dimensions:(Quantity: 2000pcs/reel)



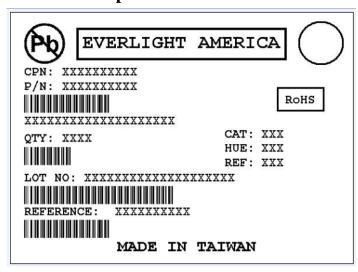
Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm



Packing Procedure



Label Form Specification



CPN: Customer's Production Number

P/N : Production Number QTY: Packing Quantity

CAT: Ranks

HUE: Peak Wavelength

REF: Reference

LOT No: Lot Number

MADE IN TAIWAN: Production Place

Notes

- 1. Above specification may be changed without notice. Everlight Americas will reserve authority on material change for above specification.
- 2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. Everlight Americas assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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